

## 1. Product Information

**Supplier:** JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

|                          |              |
|--------------------------|--------------|
| <b>Part Number:</b>      | CJP021SN15MK |
| <b>Package Type:</b>     | TO-220-3L-CB |
| <b>Part Description:</b> | THD/MOSFET   |
| <b>Report Date:</b>      | October-2025 |

## 2. Reliability Test Results: PASS

| Test Item                                               | Test Condition                                                                                                                                                      | Duration                     | Fail Quantity / S.S |
|---------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------|---------------------|
| Pre-and post-stress Electrical test                     | Ta=25°C                                                                                                                                                             | —                            | All parts           |
| <b>PC</b><br>Precondition(For SMD Package Only)         | JESD22-A113F/J-STD-020<br>1.Bake:125°C<br>2.Soak:<br>85°C85%RH,168Hours MSL1<br>or<br>30°C60%RH,192Hours MSL3<br>3.Reflow 3Cycles Max 260°C<br>4.all samples E-Test | >168Hours<br>or<br>>192Hours | 0 / 308*3           |
| <b>TCT</b><br>Temperature Cycling Test                  | JESD22 -A104<br>-55°C/15min 150°C/15min                                                                                                                             | 1000Cycles                   | 0 / 77*3            |
| <b>AC</b><br>Autoclave                                  | JESD22-A102<br>121°C, 100%RH                                                                                                                                        | 96Hours                      | 0 / 77*3            |
| <b>UHASt</b><br>Unbaised Highly Accelerated Stress Test | JESD22-A118<br>130°C, 85%RH                                                                                                                                         | 96Hours                      | —                   |
| <b>THt</b><br>High Humidity &Temp. Test                 | JESD22-A101<br>85°C 85%RH                                                                                                                                           | 1000Hours                    | 0 / 77*3            |
| <b>HTSt</b><br>High Temperature Storage Test            | JESD22 -A103<br>T=Tstg max                                                                                                                                          | 1000Hours                    | 0 / 77*3            |
| <b>H3TRB</b><br>High Humidity &Temp. Bias Test          | JESD22-A101<br>85°C 85%RH VDS*80% VDS≤100V Max                                                                                                                      | 1000Hours                    | —                   |
| <b>HASt</b><br>Highly Accelerated Stress Test           | JESD22-A110<br>130°C 85%RH VDS*80% VDS≤42V Max                                                                                                                      | 96Hours                      | 0 / 77*3            |
| <b>HTRB</b><br>High Temperature Revers Bias Test        | JESD22 -A108<br>Tj(max), VDS*80%                                                                                                                                    | 1000Hours                    | 0 / 77*3            |
| <b>HTGB</b><br>High Temperature Gate Bias Test          | JESD22 -A108<br>Tj(max), VGS*100%                                                                                                                                   | 1000Hours                    | 0 / 77*3            |
| <b>IOL</b><br>Intermittent Operational Life             | MIL-STD-750D Method 1037<br>ΔTj≥100°C, On/Off:2min                                                                                                                  | 15000Cycles                  | 0 / 77*3            |
| <b>RSH</b><br>Resistance to Solder Heat test            | JESD22-A111B<br>260°C±5°C, 10(+2,-0)Seconds                                                                                                                         | —                            | 0 / 30*3            |
| <b>SD</b><br>Solderability                              | J-STD-002<br>1.Steam aging: 93°C 8Hours<br>2.245°C 3~5s                                                                                                             | —                            | 0 / 10*3            |

### Notes:

1. Either H3TRB or HASt for reliability test.
2. Either AC or UHASt for reliability test.
3. Detailed MSL of the product refers to the MSL Report.

Remark: JSCJ Laboratory reserves the right of final interpretation of this report